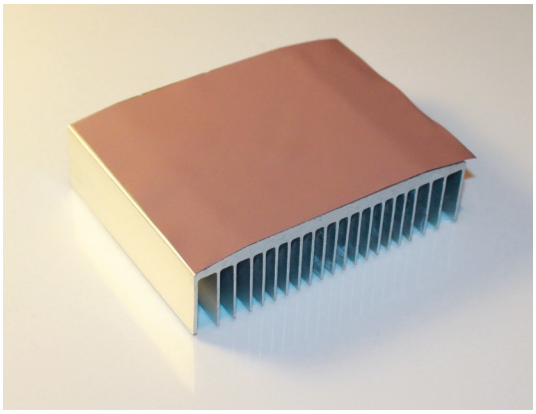
H48-2K
Thermal Conductive Pad on rolls



Features

No carrier
Low contact thermal impedance
Non-Oil Blead
High dielectric breakdown voltage

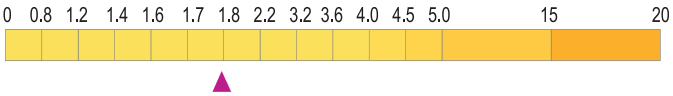
Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

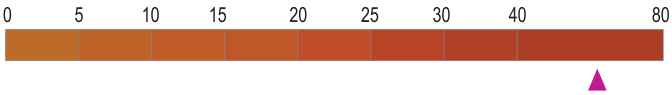
Properties

REACH Compliant
RoHS Compliant

Thermal Conductivity: 1.8 W/m.k
(W / m.k - Z Axis)



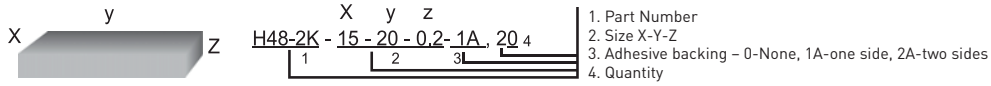
Hardeness: 60 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts H48-2K provides low thermal impedance.
As the pressure increases the thermal impedance decreases. H48-2K provides good compliance and softness.

Property	H48-2K	Unit	Test Method
Thickness	0.1/ 0.15 / 0.2 / 0.3	mm	-
Color	Dark Red	-	Visual
Construction	Silicone based with ceramic fillers (non-silicone oil)	-	-
Opt.Temp. Range	-45 to 200	˚C	-
Density	2.1	g/cm^3	ASTM D792
Thermal Conductivity	1.8	W/m.k	ASTM D5470
Hardness Shore A	60	-	ASTM D2240
Thermal impedance			ASTM D5470
10psi	0.21/0.37/0.57	K- in^2/W	-
50psi	0.20/0.33/0.51	K- in^2/W	-
100psi	0.17/0.31/0.46	K- in^2/W	-
Percent deflection			ASTM D575
10psi	2	%	-
50psi	5	%	-
100psi	11	%	-
Breakdown voltage	1.2 / 2.5 / 3.5	kV	ASTM D149
TML	‹ 0.5%	%	ASTM E595
Tensile strength	200	Psi	ASTM D412
Elongation	50	%	ASTM D412
UL flammability	V-0	-	UL 94
Roll Length / Width	50 - 320	Metres / mm	-

Available with an adhesive backing



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